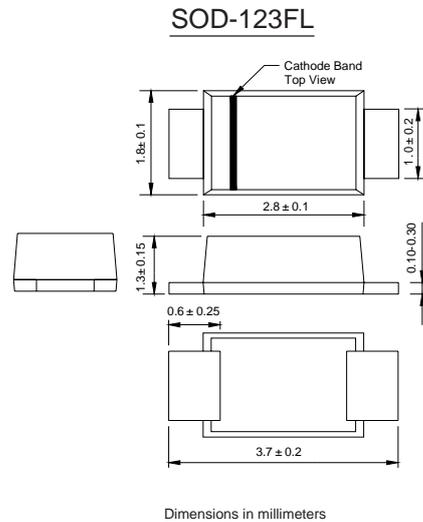


Features

- For surface mounted applications in order to optimize board space
- Low profile space
- Low Zener impedance
- High reliability
- For use in stabilizing and clipping circuits with high power rating.
- Component in accordance to RoHS 2002/95/EC and WEEE 2002/96/EC

Mechanical Date

- **Case:** Flat Lead SOD-123 Small Outline Plastic Package
- **Polarity:** Types the band by laser denotes the cathode
- **Terminals:** Solder plated, solderable per MIL-STD-750 Method 2026
Weight: 0.0007 ounce, 0.02 grams



Applications

- For general purpose regulation and protection applications

Maximum Ratings & Thermal Characteristics

(T_A = 25 °C unless otherwise noted)

	Symbol	VALUE	UNIT
power dissipation	P _{tot}	1	W
Thermal resistance from junction to ambient ⁽¹⁾	R _{θJA}	230	°C/ W
Operating junction temperature range	T _J	-65 to +150	°C
Storage temperature range	T _{STG}	-65 to +150	°C

These ratings are limiting values above which the serviceability of the diode may be impaired.

Note1: Mounted on FR-4 P.C.B. With 0.9x1.5 mm copper pad areas (≈35 μm thick)

Electrical Characteristics

T_A =25°C unless otherwise noted.

TYPE	Zener Voltage			Zener Impedance			Leakage Current		I _{ZM}	
	V _Z (Volts)			Z _{ZT} @I _{ZT}	Z _{ZK} @I _{ZK}		I _R @V _R			
	Min	Nom	Max	mA	Ω	Ω	mA	uA	Volts	mA
1DZ120	114	120	126	2.0	550	4500	0.25	5	91.2	7.8

Characteristic Curves ($T_A=25\text{ }^\circ\text{C}$ unless otherwise noted)

Fig. 1 - Maximum Continuous Power Dissipation

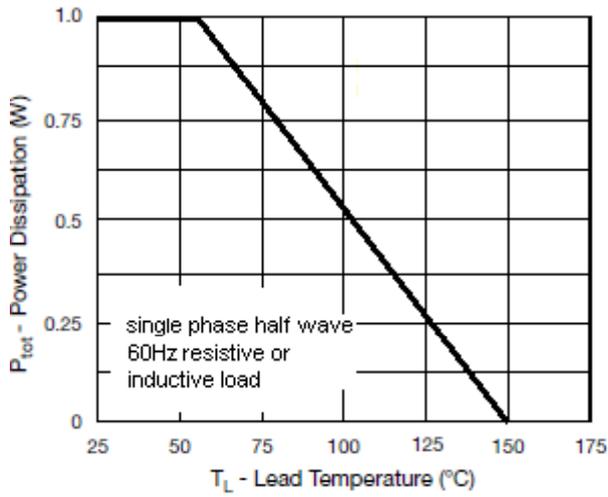


Fig. 2 - Typical Reverse Characteristics

